

IN THE SPECIFICATION:

Please insert the following paragraph on page 1 after the title of the invention and before the "TECHNICAL FIELD":

--Related Application

This application is the U.S. National Phase under 35 U.S.C. § 371 of International Application No. PCT/JP2004/003356, filed March 12, 2004, which in turn claims the benefit of Japanese Application No. 2003-096173, filed March 31, 2003, the disclosures of which Applications are incorporated by reference herein in their entirety.--

Please amend the paragraph on page 6, at line 11 as follows:

An anisotropic conductive film provided according to the present invention is ~~characterized in that an electrically insulative porous film made of synthetic resin is used as a base film and that conductive parts which can be provided with conductiveness in the film thickness direction are formed independently at plural positions of the base film by adhering conductive metal to resinous parts of porous structure in such a manner as piercing through from a first surface to a second surface.~~ , wherein an electrically insulative porous film made of synthetic resin is used as a base film and conductive metal plating particles are formed continuously adhering to the resinous parts of porous structure in the wall surfaces of through-holes piercing from a first surface to a second surface at plural positions of the base film, whereby conductive parts which can be provided with conductiveness in the film thickness direction are provided independently in a manner such that the conductive parts maintain the porous structure of the porous film.

Please amend the paragraph beginning on page 6, at line 18 and bridging page 7 as follows:

Also, a method of making an anisotropic conductive film is provided according to the present invention, ~~which method is characterized in that conductive parts which can be provided with conductiveness in the film thickness direction are formed independently at plural positions of a base film by adhering conductive metal to the resinous parts of porous structure in such a manner as piercing through from a first surface to a second surface, wherein the base film is an~~

~~electrically insulative porous film made of synthetic resin. wherein~~ conductive metal particles formed by plating are adhered continuously to the resinous parts of porous structure in the wall surface of the through-holes piercing through from a first surface to a second surface at plural positions of a base film made of an electrically insulative porous film formed synthetic resin, whereby conductive parts which can be provided with conductiveness in the film thickness direction are provided independently in a manner such that the conductive parts maintain the porous structure of the porous film.

Please amend the paragraph on page 7, at line 4 as follows:

1. A method of manufacturing an anisotropic conductive film, which method is characterized in that conductive parts capable of being afforded with conductiveness respectively in the film thickness direction are provided independently of each other ~~in a piercing manner from a first surface to a second surface by adhering conductive metal to resinous parts having porous structure at plural positions in a base film consisting of a porous polytetrafluoroethylene film, wherein~~ by adhering conductive metal particles of electroless plating continuously to the resinous parts of porous structure in the wall surfaces of through-holes piercing through from a first surface to a second surface at plural positions of a base film made of an porous polytetrafluoroethylene film formed from synthetic resin, wherein the conductive parts maintain the porous structure of the porous film, the method comprises:

Please amend the paragraph on page 7, at line 19 as follows:

(3) a step of adhering catalytic particles for facilitating chemical reduction reaction to resinous parts of porous structure existing in the whole surface, including the wall surfaces of the through-holes, of the laminated body;

Please amend the paragraph on page 8, at line 1 as follows:

(5) a step of adhering conductive metal ~~by electroless plating to resinous parts having porous structure on the wall surfaces of the through-holes.~~ particles by electroless plating

continuously to resinous parts having porous structure in the wall surfaces of the through-holes in a manner such that the conductive parts maintain the porous structure of the porous films.

Please amend the paragraph on page 8, at line 3 as follows:

2. A method of manufacturing an anisotropic conductive film, which method is characterized in that conductive parts capable of being afforded with conductiveness ~~respectively in the film thickness direction are provided independently of each other in a piercing manner from a first surface to a second surface by adhering conductive metal to resinous parts having porous structure at plural positions in a base film consisting of a porous polytetrafluoroethylene film, wherein~~ in the film thickness direction are provided independently of each other by adhering conductive metal particles of electroless plating continuously to the resinous parts of porous structure in the wall surfaces of through-holes piercing through from a first surface to a second surface at plural positions of a base film made of an porous polytetrafluoroethylene film formed from synthetic resin, wherein the conductive parts maintain the porous structure of the porous film, the method comprises:

Please amend the paragraph on page 8, at line 17 as follows:

(III) a step of adhering catalytic particles for facilitating chemical reduction reaction to resinous parts of porous structure existing in the whole surface, including the wall surfaces of the through-holes, of the laminated body;

Please amend the paragraph on page 8, at line 22 as follows:

(V) a step of adhering conductive metal by electroless plating to resinous parts having porous structure in the wall surfaces of the through-holes in a manner such that the conductive parts maintain the porous structure of the porous film.

Please amend the paragraph on page 9, at line 8 as follows:

(i) a step of forming a three layer laminated body by fusion-bonding ~~porous~~ polytetrafluoroethylene films (B) and (C) as mask layers to both surfaces of a base film consisting of a porous polytetrafluoroethylene film (A);

Please amend the paragraph on page 9, at line 19 as follows:

(v) a step of adhering catalytic particles for facilitating chemical reduction reaction to resinous parts of porous structure existing in the whole surface, including the wall surfaces of the through-holes, of the laminated body;